

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	jp-2001239395-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/15 14:49
S2	2	("5849606").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/09/15 15:35
S3	2	("5128746").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/15 14:54
S4	2167	438/108.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:03
S5	31184	228/179.1,180.21-22.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:03
S6	3239	228/179.1,180.21,180.22.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:04
S7	39	(S4 or S6) and (reinforc\$4 near10 (epoxy or resin)) and (PCB or board or substrate) same paste same (bond\$4 or solder\$3 or join\$3) same (chip or chips or component or components)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:06
S8	1168	mori-masato.in. or onishi-hiroaki.in. or hirano-masato.in. or nishida-kazuto.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:09

S9	5	S8 and (reinforc\$4 near10 (epoxy or resin)) and (PCB or board or substrate) same paste same (bond \$4 or solder\$3 or join\$3) same (chip or chips or component or components)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:10
S10	5	S8 and (reinforc\$4 near10 (epoxy or resin)) and (PCB or board or substrate) same3 paste same3 (bond \$4 or solder\$3 or join\$3) same3 (chip or chips or component or components)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:16
S11	9	S8 and (reinforc\$4 near10 (epoxy or resin)) and (PCB or board or substrate) same (bond\$4 or solder \$3 or join\$3) same (chip or chips or component or components)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:17
S12	173	(S4 or S6) and (reinforc\$4 near10 (epoxy or resin)) and (PCB or board or substrate) same (bond\$4 or solder \$3 or join\$3) same (chip or chips or component or components)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:18
S13	134	S12 not S7	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:18
S14	104	S13 and @ad<"20040224"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:18
S15	117	("4448847" "4604644" "4855001" "4980086").PN. OR ("5128746").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/15 15:31
S16	107	S15 and @ad<"20040224"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/15 15:31
S17	9	S16 and (reinforc\$4 near10 (epoxy or resin)) and (PCB or board or substrate) and (bond\$4 or solder\$3 or join\$3) same (chip or chips or component or components)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:32
S19	5	(S4 or S6 or S8) and (reinforc\$4 near10 (epoxy or resin)) near10 (appl\$4 or deposit\$3 or suppl\$4 or form\$3 of fill\$3) near10 paste and (substrate or board or PCB)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:51

S20	30	("3339274" "3959874" "4172907" "4616406" "5120678" "5148266" "5155904" "5241133" "5316788" "5397917" "5433822" "5436203" "5468681" "5581122" "5663106" "5663593" "5798563" "5824569" "5889655" "6229209").PN. OR ("6365499").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/15 16:06
S21	2	ishidoya.in. and resin and substrate and paste and solder\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 16:10
S22	4	ishidoya.in. and resin and paste and solder\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 16:11
S23	10	("5128746" "5985043" "5985456" "5985486" "6458472").PN. OR ("6667194").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/15 16:26
S24	17	("20010003058" "20020167077" "20030080437" "20030096452" "5975408" "6458472" "6475828" "6660560" "6667194").PN. OR ("6773958").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/15 16:29
S25	2167	438/108.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/16 12:51
S26	3239	228/179.1,180.21,180.22.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/16 12:51
S27	4	(S25 or S26) and resin and print\$3 near5 paste near10 (board or substrate) same2 (retain\$4 or keep \$3 or maintain\$3 or preserv\$3) near5 (shap\$3 or form or pattern or configuration)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/16 12:51

11/16/2008 2:30:16 PM

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